Global Temporary Wafer Bonding Materials and Cleaning Agents Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

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Abstracts

According to our (Global Info Research) latest study, the global Temporary Wafer Bonding Materials and Cleaning Agents market size was valued at US$ 277 million in 2024 and is forecast to a readjusted size of USD 408 million by 2031 with a CAGR of 5.4% during review period.

In this report, we will assess the current U.S. tariff framework alongside international policy adaptations, analyzing their effects on competitive market structures, regional economic dynamics, and supply chain resilience.

Temporary wafer bonding materials play a critical role in semiconductor manufacturing. They provide rigid support for ultra-thin wafers during backside processing, ensuring the wafers can withstand complex back-end operations. These materials are characterized by excellent removability and thermal stability, making them suitable for high-temperature and chemical environments. They are widely used in 3D packaging, MEMS device manufacturing, and the production of high-performance semiconductor devices. By employing temporary bonding, wafer thinning and subsequent processes can be performed while preventing damage and deformation of the wafers during handling. This report covers temporary wafer bonding materials and cleaning agents used for the removal of bonding material residues.

This report is a detailed and comprehensive analysis for global Temporary Wafer Bonding Materials and Cleaning Agents market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing

demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Temporary Wafer Bonding Materials and Cleaning Agents market size and forecasts, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/kg), 2020-2031

Global Temporary Wafer Bonding Materials and Cleaning Agents market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/kg), 2020-2031

Global Temporary Wafer Bonding Materials and Cleaning Agents market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/kg), 2020-2031

Global Temporary Wafer Bonding Materials and Cleaning Agents market shares of main players, shipments in revenue ($ Million), sales quantity (Tons), and ASP (US$/kg), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Temporary Wafer Bonding Materials and Cleaning Agents
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Temporary Wafer Bonding Materials and Cleaning Agents market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include 3M, Nikka Seiko, Brewer Science, Sekisui Chemical, Tokyo Ohka Kogyo, AI Technology, YINCAE Advanced Materials, Valtech Corporation, HD MicroSystems, Samcien Semiconductor Materials, etc.
This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Temporary Wafer Bonding Materials and Cleaning Agents market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Thermal Slip Debonding

Mechanical Debonding

Laser Debonding

Chemical Debonding

Cleaning Agents

Market segment by Application

Advanced Packaging

MEMS

CIS

Others

Major players covered

3M

Nikka Seiko

Brewer Science

Sekisui Chemical

Tokyo Ohka Kogyo

AI Technology

YINCAE Advanced Materials

Valtech Corporation

HD MicroSystems

Samcien Semiconductor Materials

Hubei Dinglong

PhiChem Corporation

Shin-Etsu Chemical

Kao Corporation

Micro Materials

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:
Chapter 1, to describe Temporary Wafer Bonding Materials and Cleaning Agents product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Temporary Wafer Bonding Materials and Cleaning Agents, with price, sales quantity, revenue, and global market share of Temporary Wafer Bonding Materials and Cleaning Agents from 2020 to 2025.
Chapter 3, the Temporary Wafer Bonding Materials and Cleaning Agents competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.
Chapter 4, the Temporary Wafer Bonding Materials and Cleaning Agents breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.
Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.
Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and Temporary Wafer Bonding Materials and Cleaning Agents market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.
Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.
Chapter 13, the key raw materials and key suppliers, and industry chain of Temporary Wafer Bonding Materials and Cleaning Agents.
Chapter 14 and 15, to describe Temporary Wafer Bonding Materials and Cleaning Agents sales channel, distributors, customers, research findings and conclusion.

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